

Amendments to the Claims:

Please amend claims 1-12 and claims 15-18 as follows.

This listing of claims replaces all prior versions, and listings, of claims in the application.

Listing of claims:

1. (Currently Amended) A ~~stack type~~ multi-chip package comprising:
a first semiconductor chip which shows good results when tested for reliability after being assembled at a package level;
at least one second semiconductor chip which is in a wafer level configuration and is stacked on the first semiconductor chip via stacking means, wherein a back surface of the first semiconductor chip abuts a back surface of the second semiconductor chip;
a first connecting unit attached to a surface opposite the back surface of the first semiconductor chip for electrically connecting the first semiconductor chip to an external system;
and
a second connecting unit attached to a surface opposite the back surface of the second semiconductor chip for electrically connecting the second semiconductor chip to the external system,
wherein the first connecting unit is different from the second connecting unit.
2. (Currently Amended) The ~~stack type~~ multi-chip package of claim 1, further comprising a printed circuit board for the multi-chip package, which includes bonding pads to which the first connecting unit and the second connecting unit are connected, and pins for connecting the bonding pads to the external system.
3. (Currently Amended) The ~~stack type~~ multi-chip package of claim 2, further comprising a molding compound for fastening the first and second semiconductor chips and protecting the first and second semiconductor chips from the external environment.

4. (Currently Amended) The ~~stack type~~ multi-chip package of claim 3, wherein the stacking means are an adhesive.

5. (Currently Amended) The ~~stack type~~ multi-chip package of claim 4, wherein [[the]]a package type of the first semiconductor chip is a Fine Ball Grid Array (FBGA) or a Wafer-Level Chip Size Package (W-CSP).

6. (Currently Amended) The ~~stack type~~ multi-chip package of claim 5, wherein the first connecting unit is a solder bump for connecting solder balls of the FBGA or the W-CSP to the bonding pads of the printed circuit board,

the second connecting unit is bonding wires for connecting pads of the second semiconductor chip to the bonding pads of the printed circuit board.

7. (Currently Amended) The ~~stack type~~ multi-chip package of claim 6, wherein [[the]]a package type of the printed circuit board is a Ball Grid Array (BGA).

8. (Currently Amended) The ~~stack type~~ multi-chip package of claim 7, wherein the first semiconductor chip and the second semiconductor chip are stacked via the adhesive such that their the back surface surfaces of the first semiconductor chip faces the back surface of the second semiconductor chip face each other.

9. (Currently Amended) The ~~stack type~~ multi-chip package of claim 4, wherein [[the]]a package type of the first semiconductor chip is a Thin Quad Flat package (TQFP) or a Super Thin Small Outline Package (STSOP).

10. (Currently Amended) The ~~stack type~~ multi-chip package of claim 9, wherein the first connecting unit is a solder bump for connecting pins of the TQFP or the STSOP to the bonding pads of the printed circuit board,

the second connecting unit is bonding wires for connecting pads of the second semiconductor chip to the bonding pads of the printed circuit board.

11. (Currently Amended) The ~~stack type~~ multi-chip package of claim 10, wherein ~~[[the]]~~a package type of the printed circuit board is a BGA.

12. (Currently Amended) The ~~stack type~~ multi-chip package of claim 10, wherein ~~[[the]]~~a package type of the printed circuit board is a TQFP.

13. (Withdrawn) The stack type multi-chip package of claim 11, wherein one surface, on which pads of the first semiconductor chip are disposed, faces and is stacked on a back surface of the second semiconductor chip via the adhesive.

14. (Withdrawn) The stack type multi-chip package of claim 12, wherein one surface, on which pads of the first semiconductor chip are disposed, faces and is stacked on a back surface of the second semiconductor chip via the adhesive.

15. (Currently Amended) The ~~stack type~~ multi-chip package of claim 4, wherein ~~[[the]]~~a package type of the first semiconductor chip is a BGA.

16. (Currently Amended) The ~~stack type~~ multi-chip package of claim 15, wherein the first connecting unit is a solder bump for connecting solder balls of the BGA to the bonding pads of the printed circuit board,

the second connecting unit is bonding wires for connecting pads of the second semiconductor chip to the bonding pads of the printed circuit board.

17. (Currently Amended) The ~~stack type~~ multi-chip package of claim 16, wherein ~~[[the]]~~a package type of the printed circuit board is a TQFP.

Application Number 10/714,801
Amendment dated February 8, 2006
Reply to Office Action of November 8, 2005

18. (Currently Amended) The ~~stack-type~~ multi-chip package of claim 17, wherein the first semiconductor chip and the second semiconductor chip are stacked via the adhesive such that ~~their~~ the back surface surfaces of the first semiconductor chip faces the back surface of the second semiconductor chip face each other.